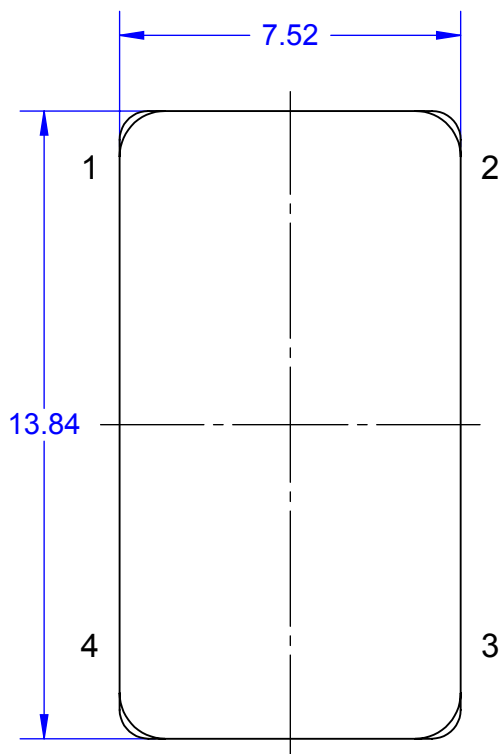
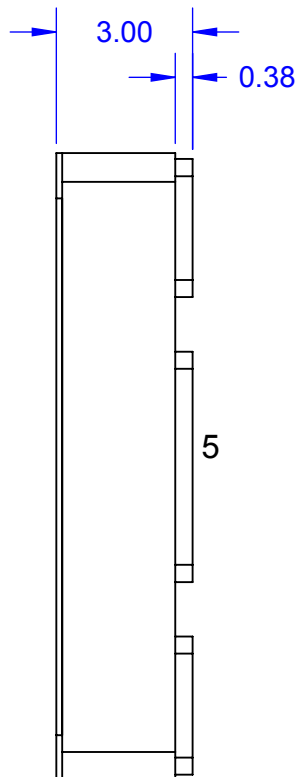


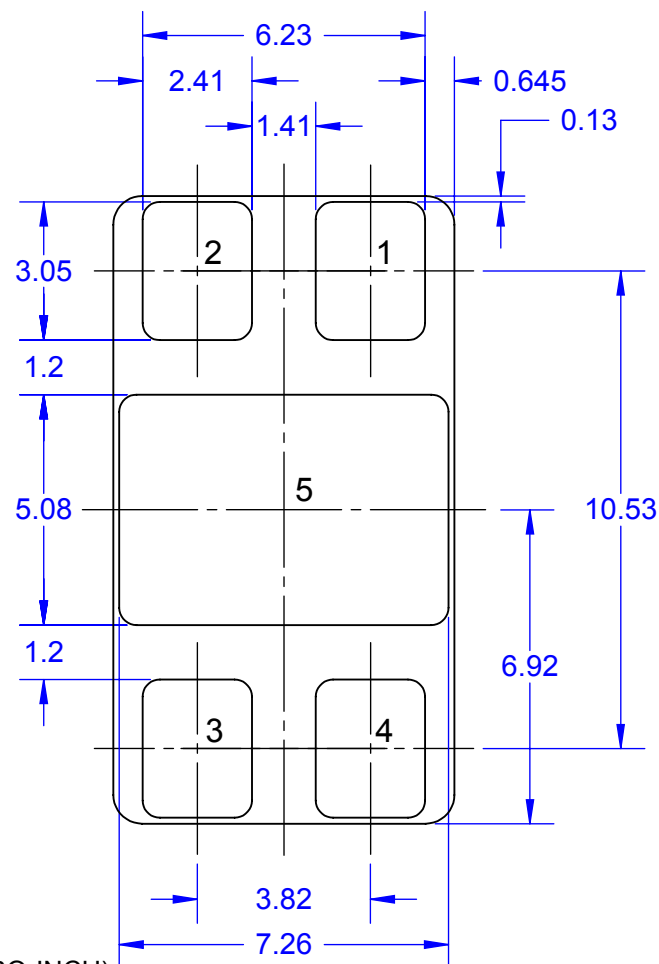
TOP VIEW SHOWN WITH LID



SIDE VIEW



BOTTOM VIEW



NOTES:

1. DIMENSIONS MM (UNLESS OTHERWISE SPECIFIED).

2. MATERIAL


FRAME: KOVAR-ALLOY F-15 ASTM.
 CERAMIC: 90% ALUMINUM OXIDE, BLACK.
 BOND PADS: 85% TUNGSTEN, 15% COPPER.
 METALIZATION: MOLY-MANGANESE.

3. Plating:

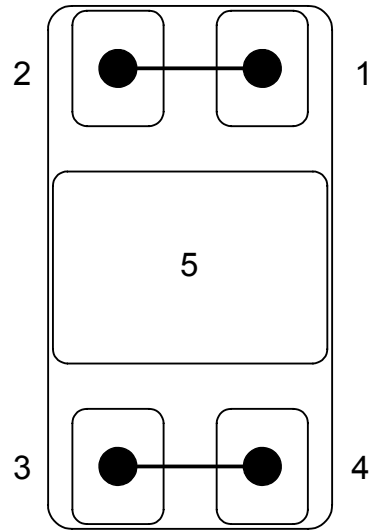
NICKEL (Ni) 2.54~8.9µm (100~350 MICRO-INCH).
 GOLD (Au) 1.27~3.8µm (50~150 MICRO INCH).

PART NUMBER TABLE

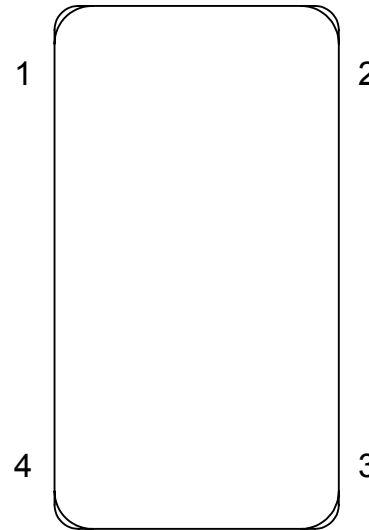
PART NUMBER	PLATING	DAISY CHAIN	DUMMY DIE	ATTACHED LID	DWG NUMBER
SMD5C-N	Ni Au	NO	NO	NO	800300
SMD5C-ISO	Ni Au	NO	NO	YES	800301
SMD5C-DC1234	Ni Au	YES	NO	YES	800302
SMD5C-DC1234-SC	SnPb	YES	NO	YES	800304
SMD5C	Ni Au	NO	NO	YES	800309
LID SMD5C	Ni	-	-	UNATTACHED	200300

APPROVALS	DATE				
DRAWN T. Au	06/22/14				
ENG M. Hart	06/22/14	TITLE SMD5C 5LD POWER PACKAGE			
MFG		SCALE 6:1	SIZE A	DRAWING NO. 800300	REV A
QA					
CUST					
REVISED		DO NOT SCALE DRAWING			SHEET 1 OF 6

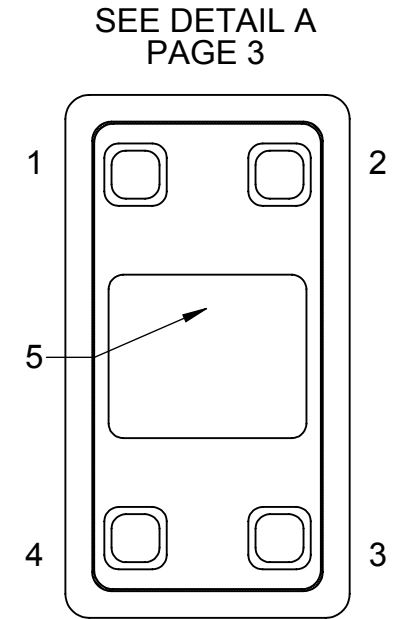
INTERNAL WIRING CIRCUIT (JUMPER) DAISY CHAIN PART NUMBER SUFFIX



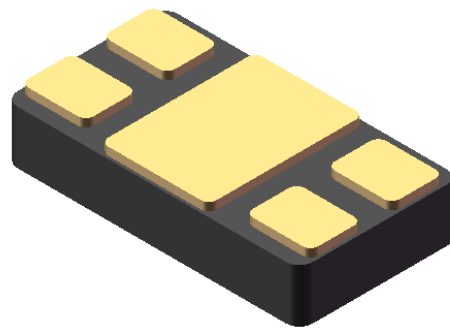
DC1234
DAISY CHAIN
BOTTOM VIEW



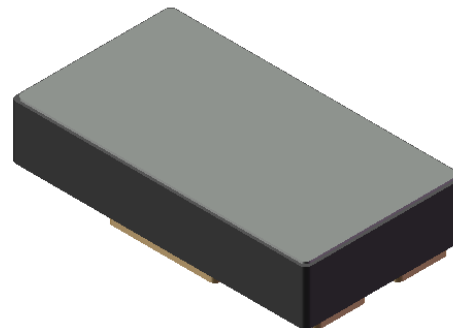
TOP VIEW
LID ATTACHED



OPTION - N
OPEN CAVITY
WITHOUT LID ATTACHED



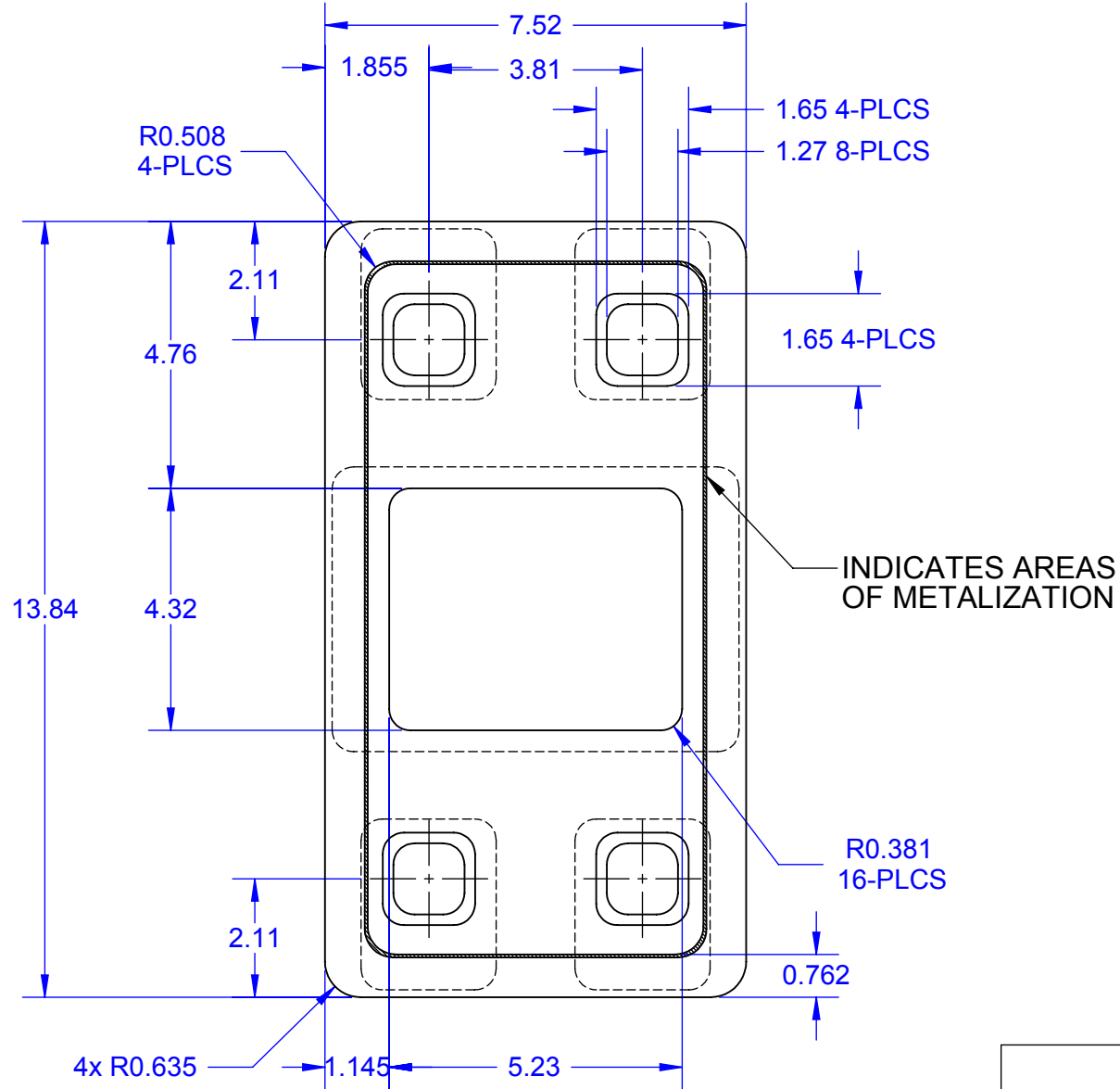
BOTTOM
VIEW OF TERMINALS



TOP
LID ATTACHED

TopLine®			
TITLE		SMD5C 5LD POWER PACKAGE	
SCALE	SIZE	DRAWING NO.	REV
5:1	A	800300	A
DO NOT SCALE DRAWING			SHEET 2 OF 6

DETAIL A INSIDE CAVITY



TopLine®

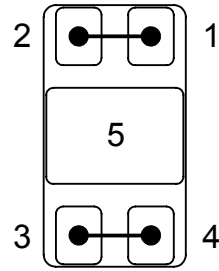
TITLE SMD5C
5LD POWER PACKAGE

SCALE	SIZE	DRAWING NO.	REV
8:1	A	800300	A

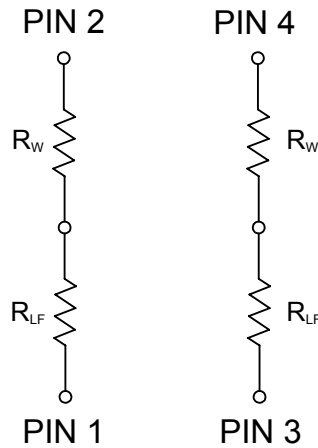
DO NOT SCALE DRAWING

SHEET 3 OF 6

SCHEMATIC EQUIVALENT INTERNAL CIRCUIT



BOTTOM VIEW



R_w = GOLD WIRE-BOND

R_{LF} = LEAD FRAME

ELECTRICAL RESISTANCE MILLIOHM (DC) MAX		
CIRCUIT	PIN 1 TO 2	PIN 3 TO 4
DC1234	< 100 mΩ	< 100 mΩ

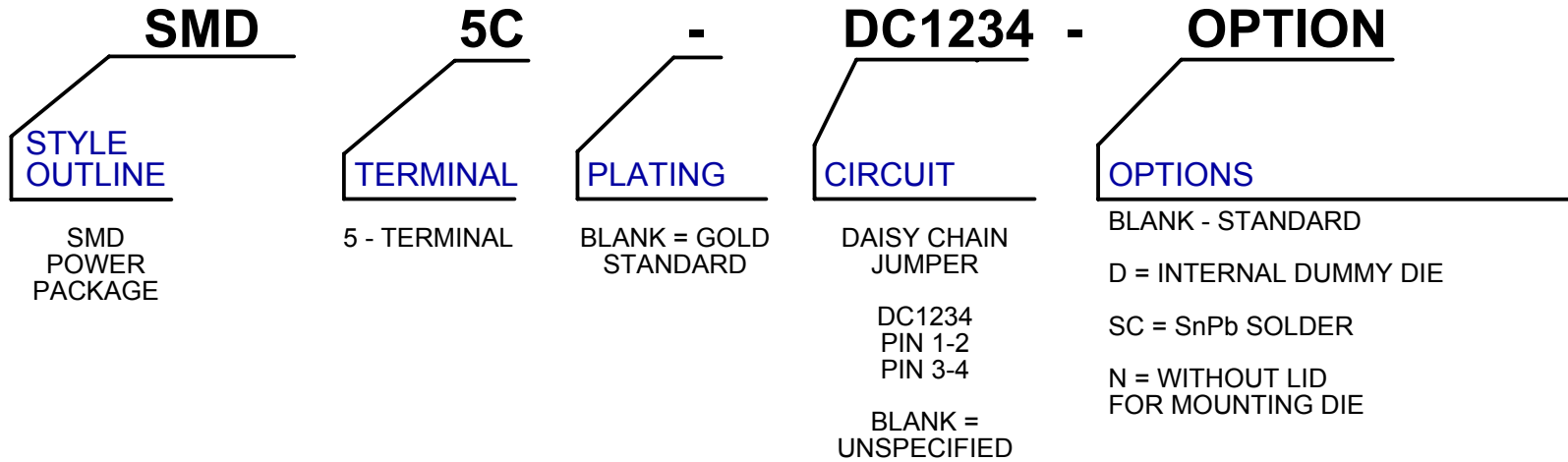
BILL OF MATERIAL		
ITEM	COMPONENT NAME	MATERIAL
1	FRAME	KOVAR-ALLOY F-15
2	CERAMIC	AL203 90% BLACK
3	BIG PAD	W85CU15
4	FOUR SMALL PADS	W 85%, Cu 15%

NOTES:
GENERAL SPECIFICATIONS COMPLY WITH MIL-STD-750E AND SCREENED PER MIL-PRF-38354.

1. MATERIAL: SEE BOM.
2. FINAL FINISH: GOLD (Au) 1.27~3.8μm (50~150 MICRO INCH) OVER NICKEL (Ni) 2.54~8.9μm (100~350 MICRO-INCH)
3. PARTS EQUAL OR EXCEED 10¹⁰ OHMS ISOLATION TEST WITH 500VDC PINS TO CASE.
4. BREAKDOWN VOLTAGE: 1000V BREAKDOWN VOLTAGE TEST WITH NORMAL TESTING CONDITIONS (PADS AND CASE).

TopLine®			
TITLE		SMD5C 5LD POWER PACKAGE	
SCALE	SIZE	DRAWING NO.	REV
2.5:1	A	800300	A
DO NOT SCALE DRAWING			SHEET 4 OF 6

PART NUMBERING SYSTEM

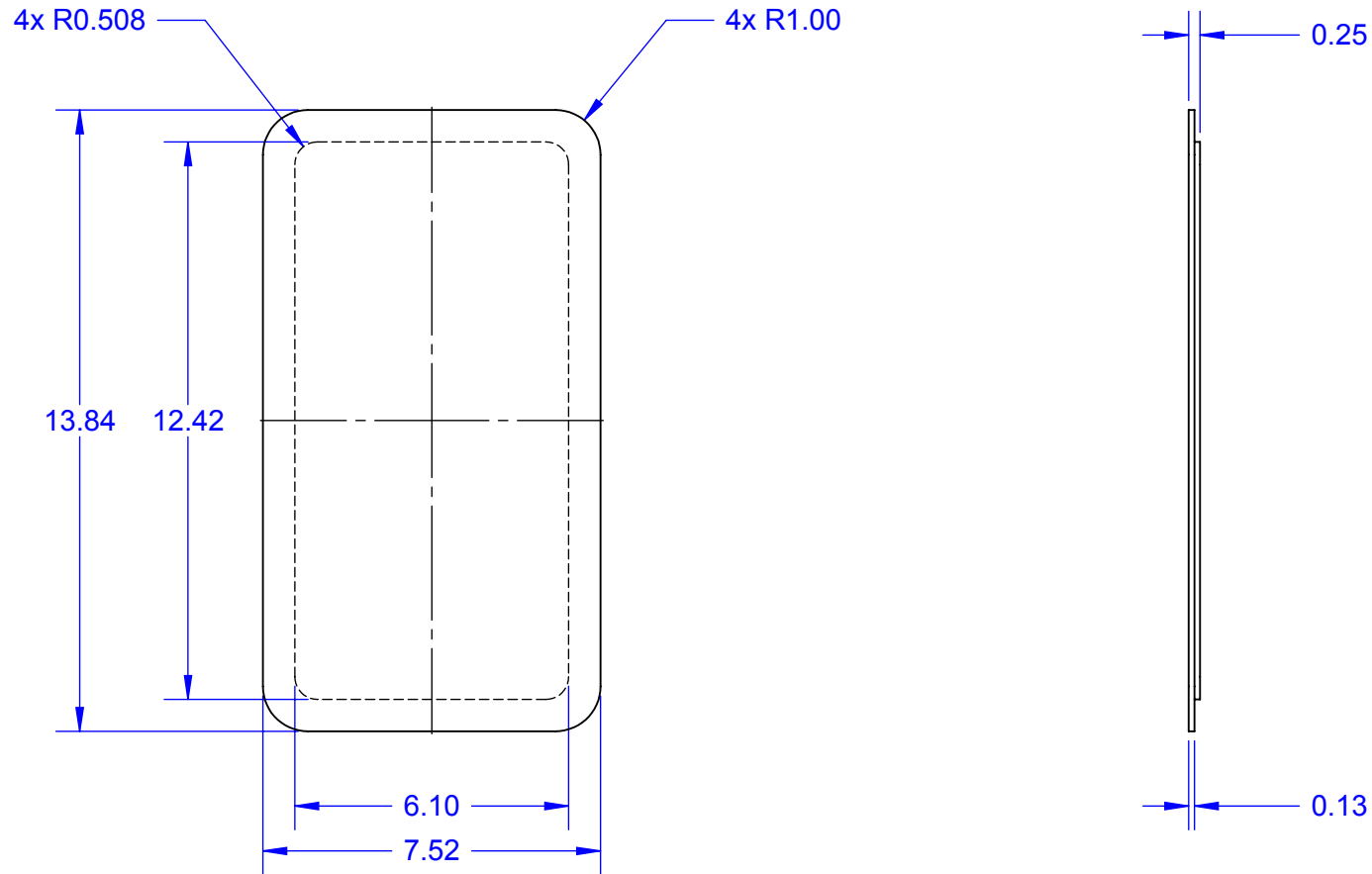


PART NUMBER	SHORTED PINS	NOTES	SEALED LID	DUMMY DIE
SMD5C	N/A	DUMMY	YES	N/A
SMD5C-D	N/A	DUMMY	YES	YES
SMD5C-N	NONE	ISOLATED	NO	NO
SMD5C-DC1234	1 ~ 2, 3 ~ 4	DAISY CHAIN	YES	NO
SMD5C-DC1234-D	1 ~ 2, 3 ~ 4	DAISY CHAIN	YES	YES
SMD5C-DC1234-SC	1 ~ 2, 3 ~ 4	DAISY CHAIN	YES	NO
SMD5C-DC1234-SC-D	1 ~ 2, 3 ~ 4	DAISY CHAIN	YES	YES

TopLine®

TITLE SMD5C 5LD POWER PACKAGE			
SCALE NONE	SIZE A	DRAWING NO. 800300	REV A
DO NOT SCALE DRAWING			SHEET 5 OF 6

STEP LID



NOTES:

1. DIMENSION in MM (UNLESS OTHERWISE SPECIFIED)
2. MATERIAL: KOVAR.
3. FINAL FINISH: ELECTROLESS NICKEL (Ni) 2.54 μ m (100 MICRO-INCH)

TopLine[®]			
TITLE		SMD5C 5LD POWER PACKAGE	
SCALE	SIZE	DRAWING NO.	REV
6:1	A	800300	A
DO NOT SCALE DRAWING			SHEET 6 OF 6